

LM185-2.5-N/LM285-2.5-N/LM385-2.5-N Micropower Voltage Reference Diode

Check for Samples: LM185-2.5-N, LM285-2.5-N, LM385-2.5-N

FEATURES

- ±20 mV (±0.8%) max. Initial Tolerance (A Grade)
- Operating Current of 20 µA to 20 mA
- 0.6Ω Dynamic Impedance (A Grade)
- **Low Temperature Coefficient**
- Low Voltage Reference—2.5V
- 1.2V Device and Adjustable Device Also Available—LM185-1.2 Series and LM185 Series, respectively

DESCRIPTION

LM185-2.5-N/LM285-2.5-N/LM385-2.5-N micropower 2-terminal band-gap voltage regulator diodes. Operating over a 20 µA to 20 mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM-185-2.5-N band-gap reference uses only transistors and resistors, low noise and good long term stability result.

Careful design of the LM185-2.5-N has made the device exceptionally tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185-2.5-N makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life. Further, the wide operating current allows it to replace older references with a tighter tolerance part. For applications requiring 1.2V see LM185-1.2.

The LM185-2.5-N is rated for operation over a −55°C to 125°C temperature range while the LM285-2.5-N is rated -40°C to 85°C and the LM385-2.5-N 0°C to 70°C. The LM185-2.5-N/LM285-2.5-N are available in a hermetic TO package and the LM285-2.5-N/LM385-2.5-N are also available in a low-cost TO-92 molded package, as well as SOIC and SOT-23. The LM185-2.5-N is also available in a hermetic leadless chip carrier package.

Connection Diagram

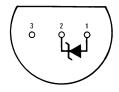


Figure 1. TO-92 Package (Bottom View) See Package Number LP0003A

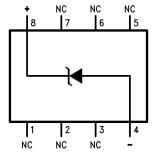


Figure 2. SOIC Package See Package Number D0008A

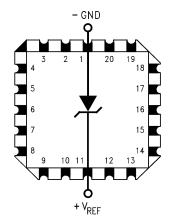


^{*} Pin 3 is attached to the Die Attach Pad (DAP) and should be connected to Pin 2 or left floating.

Figure 3. SOT-23

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1 2 0

Figure 4. LCCC Leadless Chip Carrier See Package Number NAJ0020A

Figure 5. TO Package (Bottom View) See Package Number NDU0002A



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)(2)(3)

Reverse Current			30 mA		
Forward Current			10 mA		
	LM185-2.5-N		-55°C to + 125°C		
Operating Temperature Range (4)	LM285-2.5-N		-40°C to + 85°C		
	LM385-2.5-N		0°C to 70°C		
ESD Susceptibility ⁽⁵⁾	2kV				
Storage Temperature			−55°C to + 150°C		
	TO-92 Package (10 sec.)		260°C		
Coldoring Information	TO Package (10 sec.)		300°C		
Soldering Information	COIC and COT 22 Pasterns	Vapor Phase (60 sec.)	215°C		
	SOIC and SOT-23 Package	Infrared (15 sec.)	220°C		

- 1) Refer to RETS185H-2.5 for military specifications.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) For elevated temperature operation, T_{J MAX} is:

LM185-N: 150°C LM285-N: 125°C LM385-N: 100°C

See THERMAL CHARACTERISTICS.

(5) The human body model is a 100 pF capacitor discharged through a 1.5 k Ω resistor into each pin.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	LM185	150°C			
Thermal Decistores	LM285	125°C	6010.0	SOT-23	
Thermal Resistance	LM385	100°C	SOIC-8	501-23	
	TO-92	то			
θ _{ja} (Junction to Ambient)	180°C/W (0.4" Leads)	440°C/W	165°C/W	283°C/W	
	170°C/W (0.125" Leads)				
θ _{jc} (Junction to Case)	N/A	80°C/W	N/A	N/A	





ELECTRICAL CHARACTERISTICS

			LM385	A-2.5-N	
Donomoston	Conditions	T	LM385	AX-2.5-N	Units
Parameter	Conditions	Тур	LM385/	AY-2.5-N	(Limits)
			Tested Limit ⁽²⁾	Design Limit ⁽³⁾	
Reverse Breakdown	I _R = 100 μA	2.500	2.480		V(Min)
Voltage			2.520		V(Max)
		2.500		2.470	V(Min)
				2.530	V(Max)
Minimum Operating		12	18	20	μA
Current					(Max)
Reverse Breakdown	I _{MIN} ≤ I _R ≤ 1mA		1	1.5	mV
Voltage Change with					(Max)
Current	1 mA ≤ I _R ≤ 20 mA		10	20	mV
					(Max)
Reverse Dynamic	$I_R = 100 \mu A$,	0.2		0.6	Ω
Impedance	f = 20 Hz			1.5	
Wideband Noise (rms)	I _R = 100 μA	120			μV
	10 Hz ≤ f ≤ 10 kHz				
Long Term Stability	I _R = 100 μA, T = 1000 Hr,	20			ppm
	$T_A = 25^{\circ}C \pm 0.1^{\circ}C$				
Average Temperature Coefficient ⁽⁴⁾	$I_{MIN} \le I_R \le 20 \text{ mA}$				
	X Suffix		30		ppm/°C
	Y Suffix		50		(Max)
	All Others			150	

Parameters identified with boldface type apply at temperature extremes. All other numbers apply at $T_A = T_J = 25^{\circ}C$.

Specified and 100% production tested.

Specified, but not 100% production tested. These limits are not used to calculate average outgoing quality levels.

The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating T_{MAX} and T_{MIN} , divided by $T_{MAX}-T_{MIN}$. The measured temperatures are -55° C, -40° C, 0° C, 25° C, 70° C, 85° C, 125° C.



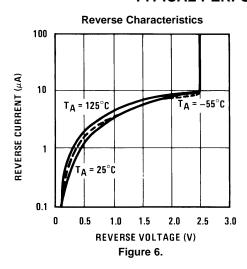
ELECTRICAL CHARACTERISTICS

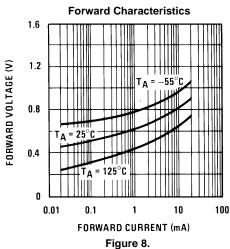
			LM185-2.5-	-N	I MOOE	B-2.5-N			
			LM185BX-2.	5-N	LIVISOS	D-2.3-N			
			LM185BY-2.	LM385E	3X-2.5-N	I MOOF	0.5 N		
Parameter	Conditions	Тур	LM285-2.5-			LM385	Units		
T drameter	Conditions	1,75	LM285BX-2.	LM285BX-2.5-N		3Y-2.5-N			(Limit)
			LM285BY-2.						
			Tested Limit ⁽¹⁾⁽²⁾	Design Limit ⁽³⁾	Tested Limit ⁽¹⁾	Design Limit ⁽³⁾	Tested Limit ⁽¹⁾	Design Limit ⁽³⁾	
Reverse Breakdown	T _A = 25°C,	2.5	2.462		2.462		2.425		V(Min)
Voltage	20 μA ≤ I _R ≤ 20 mA		2.538		2.538		2.575		V(Max)
Minimum Operating Current		13	20	30	20	30	20	30	μΑ (Max)
	LM385M3-2.5-N						15	20	
Reverse Breakdown Voltage Change	20 μA ≤ I _R ≤ 1 mA		1	1.5	2.0	2.5	2.0	2.5	mV (Max)
with Current	1 mA ≤ I _R ≤ 20 mA		10	20	20	25	20	25	mV (Max)
Reverse Dynamic	$I_R = 100 \mu A$,	1							Ω
Impedance	f = 20 Hz								
Wideband Noise (rms)	$I_R = 100 \mu A$, 10 Hz $\leq f \leq 10 \text{ kHz}$	120							μV
Long Term Stability	$I_R = 100 \mu A$								
	T = 1000 Hr,	20							ppm
	$T_A = 25^{\circ}C \pm 0.1^{\circ}C$								
Average	I _R = 100 μA								
Temperature Coefficient ⁽⁴⁾	X Suffix		30		30				ppm/°C
Cocincient	Y Suffix		50		50				ppm/°C
	All Others			150		150		150	ppm/°C
									(Max)

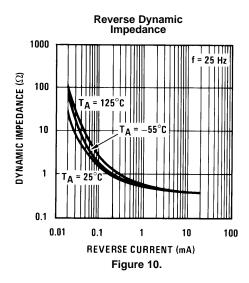
 ⁽¹⁾ Specified and 100% production tested.
 (2) A military RETS electrical specification available on request.
 (3) Specified, but not 100% production tested. These limits are not used to calculate average outgoing quality levels.
 (4) The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating T_{MAX} and T_{MIN} , divided by $T_{MAX}-T_{MIN}$. The measured temperatures are $-55^{\circ}C$, $-40^{\circ}C$, $0^{\circ}C$, $25^{\circ}C$, $70^{\circ}C$, $85^{\circ}C$, $125^{\circ}C$.

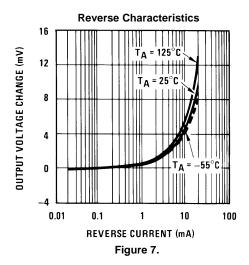


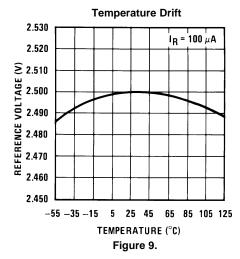
TYPICAL PERFORMANCE CHARACTERISTICS

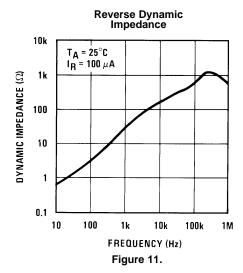






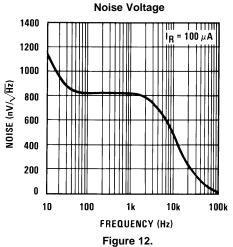


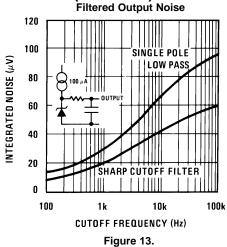


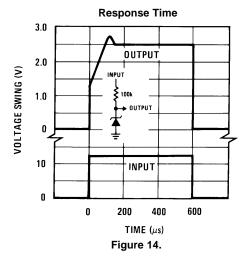




TYPICAL PERFORMANCE CHARACTERISTICS (continued)









APPLICATIONS

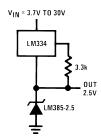


Figure 15. Wide Input Range Reference

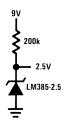


Figure 16. Micropower Reference from 9V Battery

LM385-2.5-N Applications

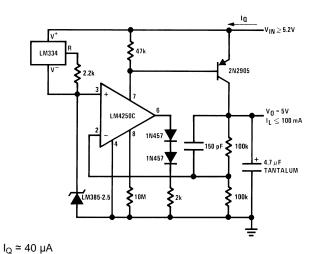


Figure 17. Micropower 5V Reference

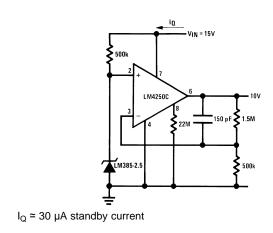
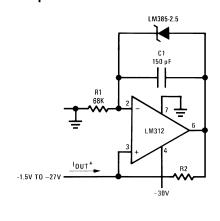


Figure 18. Micropower 10V Reference

PRECISION 1 µA to 1 mA CURRENT SOURCES



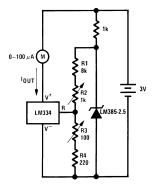
1.5V TO 27V

Figure 19.

METER THERMOMETERS

 \bullet I_{OUT} = $\frac{2.5V}{R2}$





10UT V+ R2 Ik IM385-2.5 V- R3 F000

Calibration

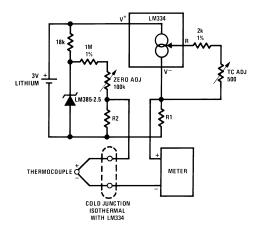
- 1. Short LM385-2.5-N, adjust R3 for $I_{OUT}\!\!=\!\!temp$ at $1\mu A/^{\circ}K.$
- 2. Remove short, adjust R2 for correct reading in centigrade

Figure 20. 0°C-100°C Thermomemter

Calibration

- 1. Short LM385-2.5-N, adjust R3 for I_{OUT} =temp at 1.8 μ A/°K
- 2. Remove short, adjust R2 for correct reading in °F

Figure 21. 0°F–50°F Thermomemter



Adjustment Procedure

- Adjust TC ADJ pot until voltage across R1 equals Kelvin temperature multiplied by the thermocouple Seebeck coefficient.
- 2. Adjust zero ADJ pot until voltage across R2 equals the thermocouple Seebeck coefficient multiplied by 273.2.

Figure 22. Micropower Thermocouple Cold Junction Compensator

Thermocouple Type ⁽¹⁾	Seebeck Coefficient (_µ V/°C)	R1 (Ω)	R2 (Ω)	Voltage Across R1 @25°C (mV)	Voltage Across R2 (mV)
J	52.3	523	1.24k	15.60	14.32
Т	42.8	432	1k	12.77	11.78
К	40.8	412	953Ω	12.17	11.17
S	6.4	63.4	150Ω	1.908	1.766

(1) Typical supply current 50 μA



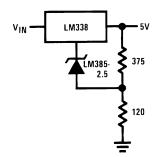
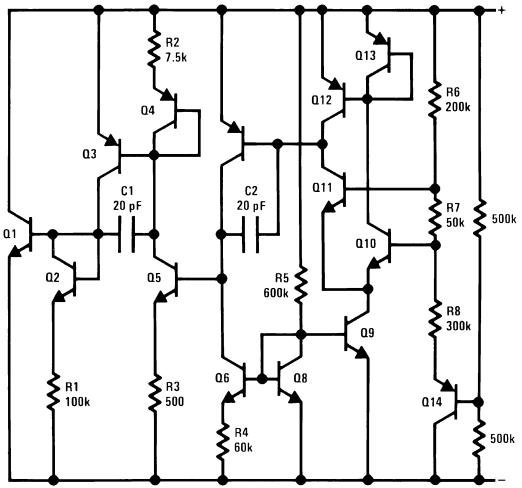


Figure 23. Improving Regulation of Adjstable Regulators

Schematic Diagram





REVISION HISTORY

Ch	nanges from Revision C (March 2013) to Revision D	Page
•	Changed layout of National Data Sheet to TI format	9



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM185H-2.5/NOPB	ACTIVE	ТО	NDU	2	1000	RoHS & Green	SNAGCU	Level-1-NA-UNLIM	-55 to 125	(LM185H2.5, LM185 H2.5)	Samples
LM285BXM-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	285BX M2.5	Samples
LM285BXMX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	285BX M2.5	Samples
LM285BXZ-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	-40 to 85	285BX Z2.5	Samples
LM285BYM-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	285BY M2.5	Samples
LM285BYMX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	285BY M2.5	Samples
LM285BYZ-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	-40 to 85	285BY Z2.5	Samples
LM285M-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M2.5	Samples
LM285MX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M2.5	Samples
LM285Z-2.5/LFT7	ACTIVE	TO-92	LP	3	2000	RoHS & Green	Call TI	N / A for Pkg Type		LM285 Z-2.5	Samples
LM285Z-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	-40 to 85	LM285 Z-2.5	Samples
LM385BM-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM2.5	Samples
LM385BMX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM2.5	Samples
LM385BXM-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	385BX M2.5	Samples
LM385BXMX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM 0 to 70		385BX M2.5	Samples
LM385BXZ-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	0 to 70	385BX Z-2.5	Samples
LM385BYM-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	385BY	Samples



PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(0)			M2.5	
LM385BYMX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	385BY M2.5	Samples
LM385BYZ-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	0 to 70	385BY Z-2.5	Samples
LM385BZ-2.5/LFT7	ACTIVE	TO-92	LP	3	2000	RoHS & Green	Call TI	N / A for Pkg Type		LM385 BZ2.5	Samples
LM385BZ-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	0 to 70	LM385 BZ2.5	Samples
LM385M-2.5/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	LM385 M2.5	Samples
LM385M3-2.5	NRND	SOT-23	DBZ	3	1000	Non-RoHS & Green	Call TI	Level-1-260C-UNLIM	0 to 70	R12	
LM385M3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	R12	Samples
LM385M3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	R12	Samples
LM385MX-2.5/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	LM385 M2.5	Samples
LM385Z-2.5/LFT1	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM385 Z2.5	Samples
LM385Z-2.5/LFT2	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM385 Z2.5	Samples
LM385Z-2.5/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	Call TI	N / A for Pkg Type	0 to 70	LM385 Z2.5	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



PACKAGE OPTION ADDENDUM

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

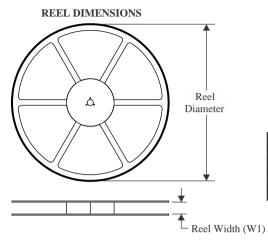
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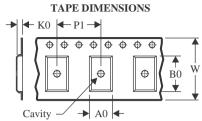
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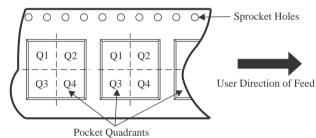
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

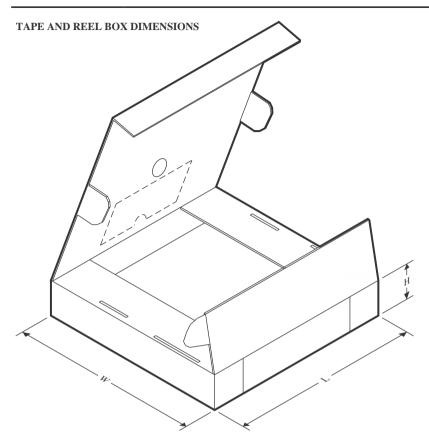


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285BXMX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285BYMX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285MX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BMX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BXMX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BYMX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385M3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385MX-2.5/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1



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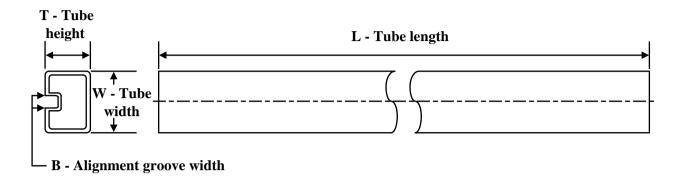
*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285BXMX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285BYMX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285MX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BMX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BXMX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BYMX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385M3-2.5	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM385M3-2.5/NOPB	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM385M3X-2.5/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM385MX-2.5/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

PACKAGE MATERIALS INFORMATION

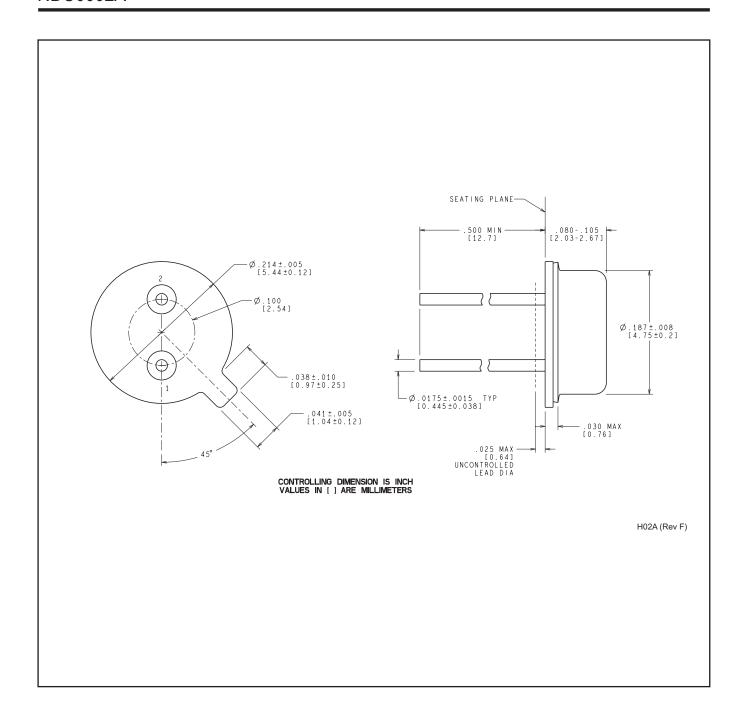
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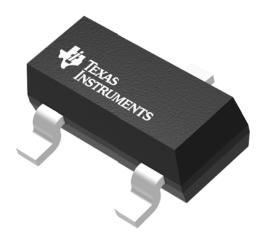
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM285BXM-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM285BYM-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM285M-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385BM-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385BXM-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385BYM-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385M-2.5/NOPB	D	SOIC	8	95	495	8	4064	3.05





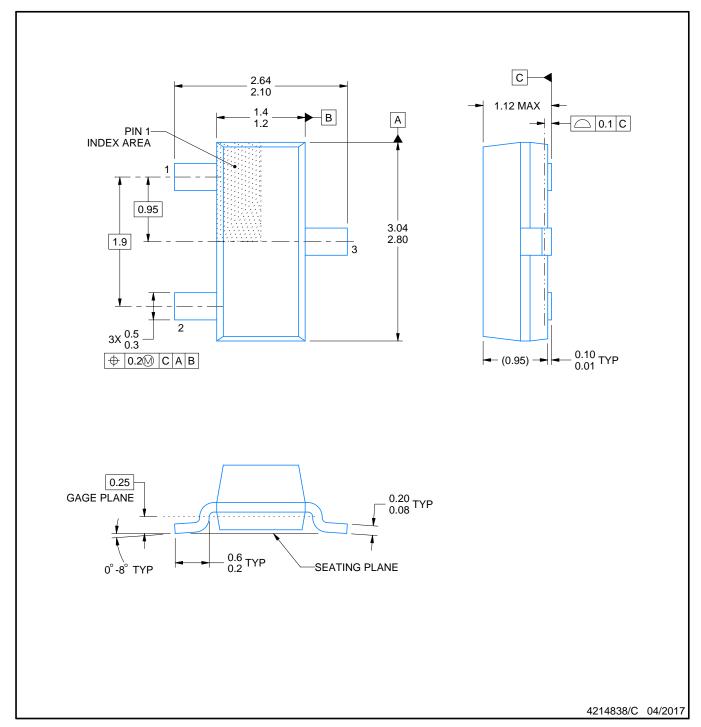
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4203227/C





SMALL OUTLINE TRANSISTOR

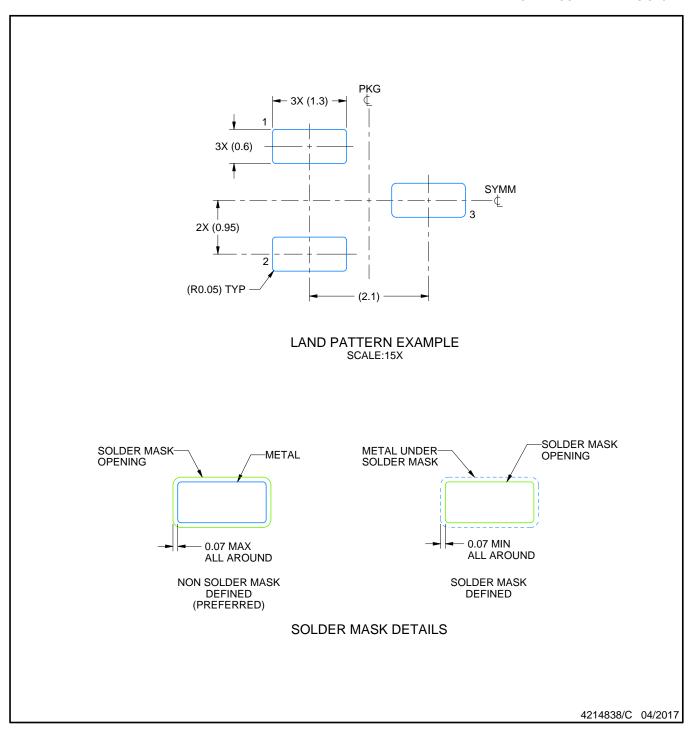


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration TO-236, except minimum foot length.



SMALL OUTLINE TRANSISTOR

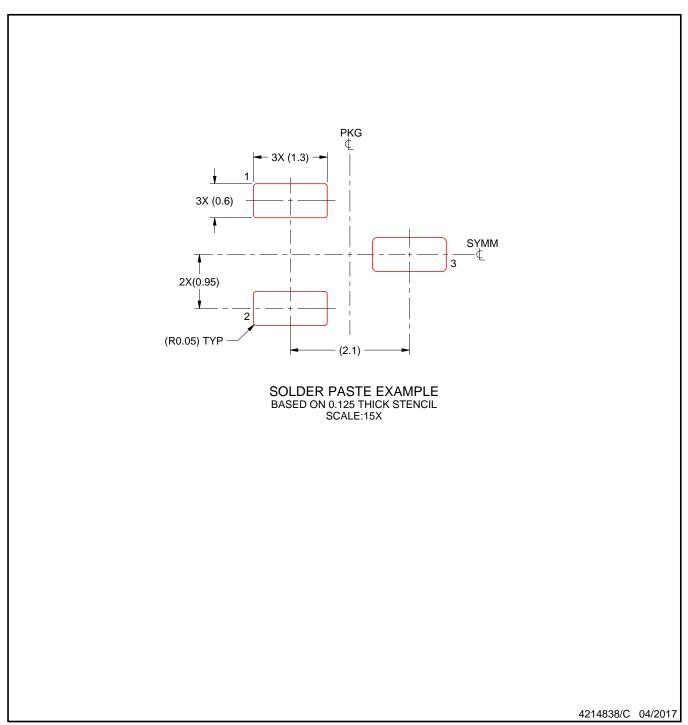


NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.





SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



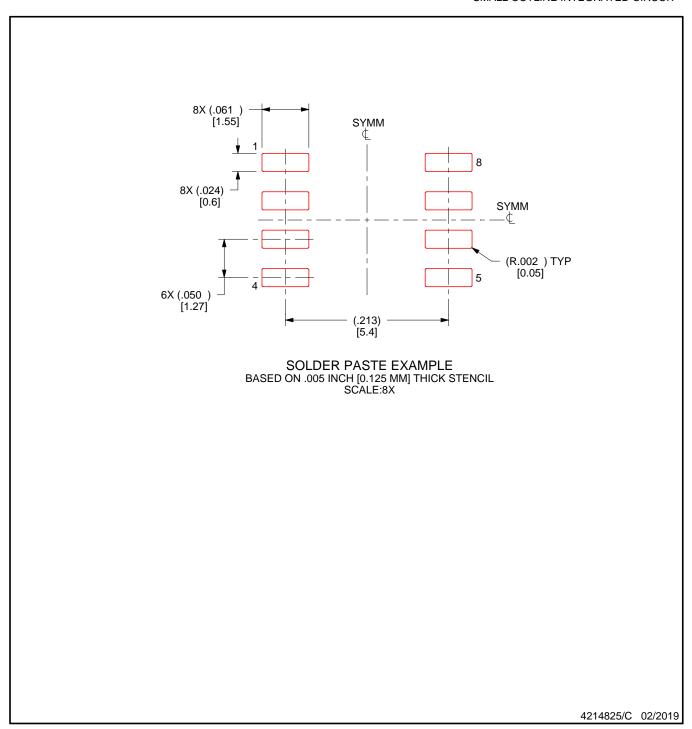
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



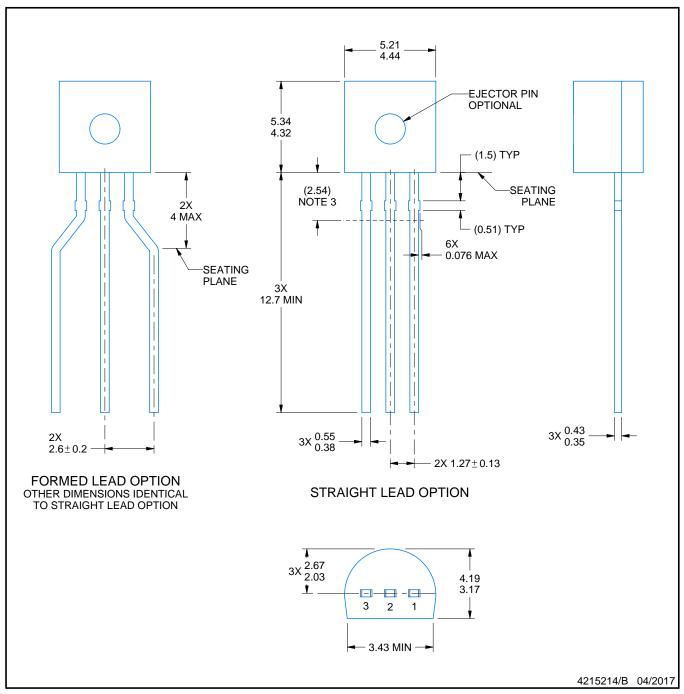


Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040001-2/F



TO-92



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- 3. Lead dimensions are not controlled within this area.4. Reference JEDEC TO-226, variation AA.
- 5. Shipping method:

 - a. Straight lead option available in bulk pack only.
 b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.



TO-92





TO-92





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ADR435BRMZ-REEL7 CA-HP6050S TL431 BR431RM MSR025 MC1403BN LM285Z-2.5 LM385B-ADJ LM385B-2.5 HT385R-1.2
HT336R-2.5 RS3450XH6-Q1 RS3412XH6-Q1